



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-09-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LM2902YDT	IDK7*0124BJ6	A	BO2A	2017-09-11
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	Package: K7 SO 14 .15 TO JEDEC MS-012			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	IDK7*0124BJ6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.292	mg	supplier	die	Silicon (Si)	7440-21-3		1.269	mg	982198	9762
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	8514	85
				supplier	Passivation	Silicon Nitride	12033-89-5		0.005	mg	3870	38
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	5418	54
				supplier	alloy	Copper (Cu)	7440-50-8		35.999	mg	966572	276915
Leadframe	Copper & its alloys	37.244	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.847	mg	22742	6515
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.051	mg	1369	392
				supplier	alloy	Zinc (Zn)	7440-66-6		0.044	mg	1181	338
				supplier	metallization	Nickel (Ni)	7440-02-0		0.278	mg	7464	2138
				supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	242	69
Precious metals	Precious metals			supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	215	62
				supplier	metallization	Silver (Ag)	7440-22-4		0.008	mg	215	62
				supplier	glue	Silver (Ag)	7440-22-4		0.435	mg	875252	3346
Die attach	Other Organic Materials	0.497	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.025	mg	50302	192
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.025	mg	50302	192
				supplier	glue	Acrylate polymer	87320-05-6		0.010	mg	20121	77
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	2012	8
				supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	2012	8
Bonding wires	Other inorganic materials	0.114	mg	supplier	wire	Copper (Cu)	7440-50-8		0.114	mg	1000000	877
Encapsulation	Other Organic Materials	90.853	mg	supplier	mold compound	Silica, vitreous	60676-86-0		78.679	mg	866003	605223
				supplier	mold compound	Epoxy Resin	29690-82-2		6.814	mg	75000	52415
				supplier	mold compound	Phenol Resin	25068-38-6		4.543	mg	50004	34946
				supplier	mold compound	Carbon black	1333-86-4		0.454	mg	4997	3492
				supplier	mold compound	Bismuth compound	7440-69-9		0.363	mg	3995	2792